# B10G3336N16DL

LDMOS 3-stage integrated Doherty MMIC
Rev. 1 — 28 September 2023

**AMMPLEON** 

Product data sheet

#### **Product profile** 1.

### 1.1 General description

The B10G3336N16DL is a 3-stage 16 W fully integrated Doherty MMIC solution using Ampleon's state of the art LDMOS technology. The carrier and peaking device, input splitter, output combiner, and output matching are integrated in a single package. This multiband device is perfectly suited as a general-purpose device in the frequency range from 3300 MHz to 3600 MHz. Available in LGA outline.

**Performance** 

Typical RF performance at  $T_{case} = 25$  °C;  $I_{Dq} = 31$  mA (driver and final stages);  $V_{GSa(peaking)} = V_{GSa(carrier)} - 0.4 V$ ; measured in an Ampleon application circuit.

Test signal	f	V <sub>DS</sub>	P <sub>L(AV)</sub>	G <sub>p</sub>	η <sub>D</sub>	ACPR <sub>5M</sub>
	(MHz)	(V)	(W)	(dB)	(%)	(dBc)
single carrier W-CDMA [1]	3450	26	1.585	34.5	34	-33
			1.995	34.5	36	-33
	3450	28	1.585	35	33	-33
			1.995	35	35	-33

<sup>[1]</sup> Test signal: 1-carrier W-CDMA; PAR = 9.9 dB.

#### 1.2 Features and benefits

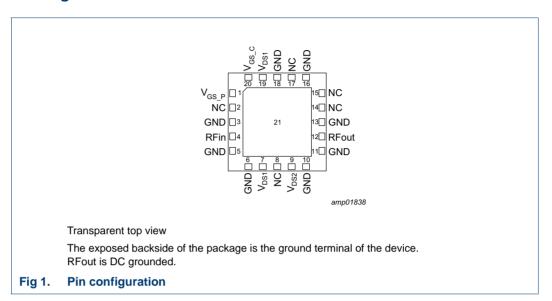
- Integrated input splitter
- Integrated output combiner
- Very high efficiency
- Designed for broadband operation (frequency 3300 MHz to 3600 MHz)
- Designed for ultra VBW
- Independent control of carrier and peaking bias
- Integrated ESD protection
- Excellent thermal stability
- $\blacksquare$  High power gain, input and output matched to impedance 50 Ω
- For RoHS compliance see the product details on the Ampleon website

### 1.3 Applications

RF power MMIC for multi-carrier and multi-standard GSM, W-CDMA, LTE and NR small cell base stations in the 3300 MHz to 3600 MHz frequency range

## 2. Pinning information

## 2.1 Pinning



## 2.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
V <sub>GS_P</sub>	1	gate-source voltage of peaking
NC	2	not connected (connection to ground is allowed)
GND	3	ground (connection to ground is required)
RFin	4	RF input
GND	5	ground (connection to ground is required)
GND	6	ground (connection to ground is required)
V <sub>DS1</sub>	7	drain-source voltage of driver stages
NC	8	not connected (connection to ground is allowed)
V <sub>DS2</sub>	9	drain-source voltage of final stages
GND	10	ground (connection to ground is required)
GND	11	ground (connection to ground is required)
RFout	12	RF output
GND	13	ground (connection to ground is required)
NC	14	not connected (connection to ground is allowed)
NC	15	not connected (connection to ground is allowed)
GND	16	ground (connection to ground is required)
NC	17	not connected (connection to ground is allowed)
GND	18	ground (connection to ground is required)

Table 2. Pin description ...continued

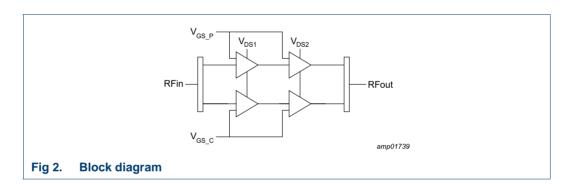
Symbol	Pin	Description
V <sub>DS1</sub>	19	drain-source voltage of driver stages
V <sub>GS_C</sub>	20	gate-source voltage of carrier
GND	21	RF ground (connection to ground is required)

## 3. Ordering information

Table 3. Ordering information

Package name	Orderable part number	12NC	Packing description	Min. orderable quantity (pieces)
LGA-7x7-20-2	B10G3336N16DLX	9349 606 42525	TR13; 3000-fold; 16 mm; dry pack	3000
	B10G3336N16DLZ	9349 606 42515	TR13; 1000-fold; 16 mm; dry pack	1000

## 4. Block diagram



## 5. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>DS</sub>	drain-source voltage		-	65	V
$V_{GS}$	gate-source voltage		-6	+11	V
T <sub>stg</sub>	storage temperature		-55	+125	°C
Tj	junction temperature	[1]	-	175	°C
T <sub>case</sub>	case temperature	[1]	-	125	°C

<sup>[1]</sup> Continuous use at maximum temperature will affect the reliability. For details refer to the online MTF calculator.

## 6. Thermal characteristics

Table 5. Thermal characteristics

Measured for total device.

Symbol	Parameter	Conditions	Value	Unit
R <sub>th(j-c)</sub>	thermal resistance from junction to	$T_{case} = 90  ^{\circ}C;  P_{L(AV)} = 1.585  W$ [1]	7.9	K/W
	case	$T_{case} = 90  ^{\circ}C;  P_{L(AV)} = 1.995  W$ [1]	8.0	K/W

<sup>[1]</sup> When operated with a 1-carrier W-CDMA with PAR = 9.9 dB.

### 7. Characteristics

#### Table 6. DC characteristics

 $T_{case} = 25$  °C; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Carrier						
$V_{GSq}$	gate-source quiescent voltage	$V_{DS} = 28 \text{ V}; I_D = 30 \text{ mA}$	1.65	2.1	2.75	V
I <sub>GSS</sub>	gate leakage current	$V_{GS} = +9 \text{ V/}-5 \text{ V}; V_{DS} = 0 \text{ V}$	-	-	140	nA
Peaking						
I <sub>GSS</sub>	gate leakage current	$V_{GS} = +9 \text{ V/}-5 \text{ V}; V_{DS} = 0 \text{ V}$	-	-	140	nA
Final sta	ges					
I <sub>DSS</sub>	drain leakage current	V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 60 V	-	-	1.4	μΑ
Driver st	Driver stages					
I <sub>DSS</sub>	drain leakage current	V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 60 V	-	-	1.4	μΑ

#### Table 7. RF characteristics

Typical RF performance at  $T_{case} = 25$  °C;  $V_{DS} = 28$  V;  $I_{Dq} = 30$  mA (carrier);  $V_{GSq(peaking)} = V_{GSq(carrier)} - 0.4$  V;  $P_L = 1.585$  W; f = 3.6 GHz. Unless otherwise specified, measured in an Ampleon production circuit.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Test sign	al: CW pulsed					
G <sub>p</sub>	power gain		32	35	-	dB
η <sub>D</sub>	drain efficiency		27	32	-	%
RLin	input return loss		-	-14	-8	dB
P <sub>L(3dB)</sub>	output power at 3 dB gain compression		41	42.5	-	dBm

## 8. Application information

#### Table 8. Typical performance

 $I_{Dq}$  = 31 mA (driver and final stages);  $V_{GSq(peaking)} = V_{GSq(carrier)} - 0.4$  V; Test signal: 1-carrier W-CDMA; PAR = 9.9 dB; unless otherwise specified, measured in an Ampleon 3300 MHz to 3600 MHz frequency band application circuit.

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
V <sub>DS</sub> = 26	V						
P <sub>L(3dB)</sub>	output power at 3 dB gain compression	f = 3450 MHz	<u>[1]</u>	-	42.5	-	dBm
η <sub>D</sub>	drain efficiency	11 dB OBO (P <sub>L(AV)</sub> = 32 dBm); f = 3450 MHz		-	34	-	%
		10 dB OBO (P <sub>L(AV)</sub> = 33 dBm); f = 3450 MHz		-	36	-	%
G <sub>p</sub>	power gain	P <sub>L(AV)</sub> = 32 dBm; f = 3450 MHz		-	34.5	-	dB
		P <sub>L(AV)</sub> = 33 dBm; f = 3450 MHz		-	34.5	-	dB
G <sub>flat</sub>	gain flatness	P <sub>L(AV)</sub> = 32 dBm; f = 3300 MHz to 3600 MHz		-	0.5	-	dB
		P <sub>L(AV)</sub> = 33 dBm; f = 3300 MHz to 3600 MHz		-	0.5	-	dB
ACPR <sub>5M</sub>	adjacent channel power ratio (5 MHz)	P <sub>L(AV)</sub> = 32 dBm; f = 3450 MHz		-	-33	-	dBc
		P <sub>L(AV)</sub> = 33 dBm; f = 3450 MHz		-	-33	-	dBc
ΔG/ΔΤ	gain variation with temperature	f = 3450 MHz		-	0.04	-	dB/°C
K	Rollett stability factor	$T_{case} = -40$ °C; f = 0.6 GHz to 8.1 GHz	[2]	-	>1	-	
V <sub>DS</sub> = 28	V						1
P <sub>L(3dB)</sub>	output power at 3 dB gain compression	f = 3450 MHz	<u>[1]</u>	-	43	-	dBm
η <sub>D</sub>	drain efficiency	11 dB OBO (P <sub>L(AV)</sub> = 32 dBm); f = 3450 MHz		-	33	-	%
		10 dB OBO (P <sub>L(AV)</sub> = 33 dBm); f = 3450 MHz		-	35	-	%
G <sub>p</sub>	power gain	P <sub>L(AV)</sub> = 32 dBm; f = 3450 MHz		-	35	-	dB
		P <sub>L(AV)</sub> = 33 dBm; f = 3450 MHz		-	35	-	dB
G <sub>flat</sub>	gain flatness	P <sub>L(AV)</sub> = 32 dBm; f = 3300 MHz to 3600 MHz		-	0.5	-	dB
		P <sub>L(AV)</sub> = 33 dBm; f = 3300 MHz to 3600 MHz		-	0.5	-	dB
ACPR <sub>5M</sub>	adjacent channel power ratio (5 MHz)	P <sub>L(AV)</sub> = 32 dBm; f = 3450 MHz		-	-33	-	dBc
		P <sub>L(AV)</sub> = 33 dBm; f = 3450 MHz		-	-33	-	dBc
ΔG/ΔΤ	gain variation with temperature	f = 3450 MHz		-	0.04	-	dB/°C
K	Rollett stability factor	$T_{case} = -40  ^{\circ}\text{C}$ ; f = 0.6 GHz to 8.1 GHz	[2]	-	>1	-	

<sup>[1]</sup> Pulsed CW power sweep measurement ( $\delta$  = 10 %,  $t_p$  = 100  $\mu$ s).

<sup>[2]</sup> S-parameters measured in a demo circuit.

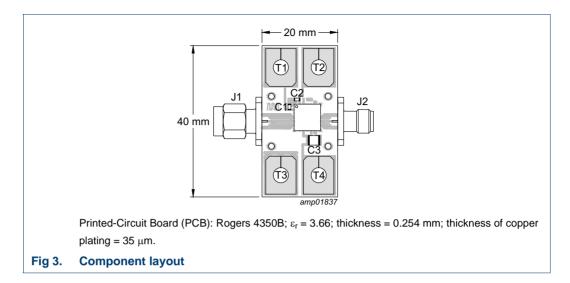


Table 9. Demo test circuit list of components

See Figure 3 for component layout.

Component	Description	Value	Remarks
C1, C2	multilayer ceramic chip capacitor	1 μF [1]	
C3	multilayer ceramic chip capacitor	10 μF [1]	
J1	coaxial panel connector male		Huber+Suhner: 13_SMA-50-0-2-/111_N
J2	coaxial panel connector female		Huber+Suhner: 23_SMA-50-0-2-/111_N
T1, T2, T3, T4	PCB terminal	6.3 mm x 0.81 mm, 4.1 mm	TE connectivity

<sup>[1]</sup> Murata or capacitor of same quality.

### 8.1 Ruggedness in a Doherty operation

#### 8.1.1 Output mismatch ruggedness

The B10G3336N16DL is capable of withstanding a load mismatch corresponding to VSWR = 10 : 1 through all phases under the following conditions:  $V_{DS}$  = 32 V;  $I_{Dq}$  = 32 mA (carrier);  $V_{GSq(peaking)} = V_{GSq(carrier)} - 0.4$  V;  $P_i$  corresponding to  $P_{L(3dB)} - 5$  dB under  $Z_S$  = 50  $\Omega$  load; f = 3600 MHz (1-carrier W-CDMA);  $T_{case}$  = 25 °C.

### 8.1.2 Wideband noise ruggedness

The B10G3336N16DL is capable of withstanding an AWGN (Additive White Gaussian Noise) with 11.2 dB PAR, OBW (Occupied BandWidth) of 900 MHz, under the following conditions:  $V_{DS} = 32$  V;  $I_{Dq} = 32$  mA (carrier);  $V_{GSq(peaking)} = V_{GSq(carrier)} - 0.4$  V; 3 dB  $P_i$  overdrive from  $P_L = 34$  dBm (corresponding to  $P_{L(3dB)} - 9$  dB); f = 3450 MHz;  $T_{case} = 25$  °C.

## 9. Package outline

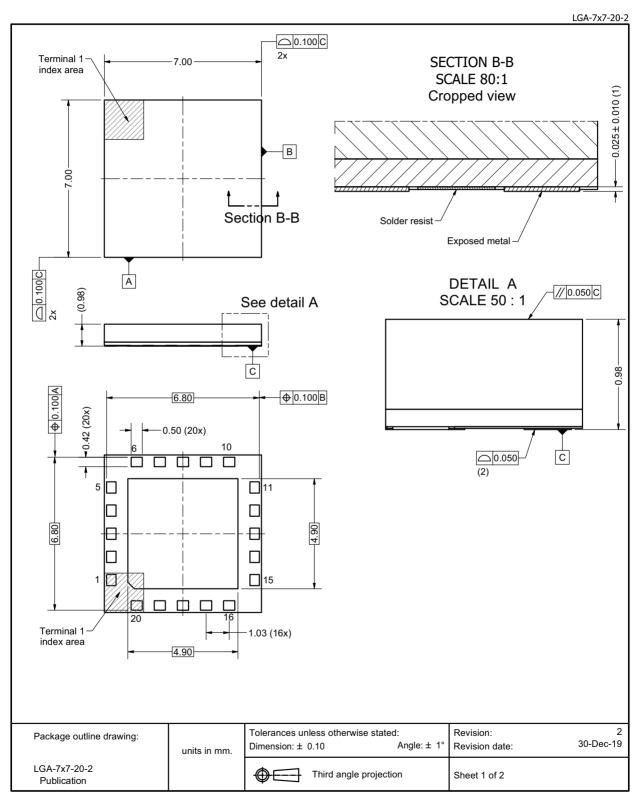


Fig 4. Package outline LGA-7x7-20-2 (sheet 1 of 2)

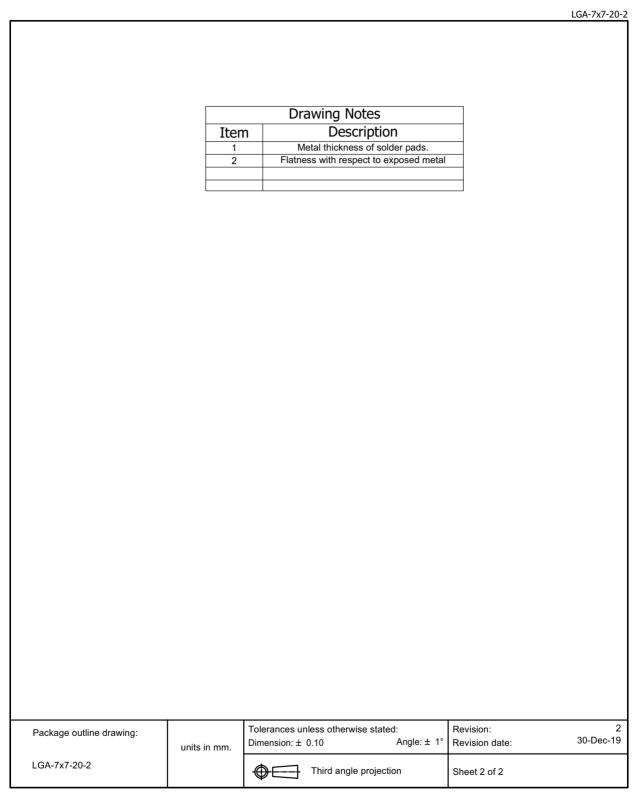


Fig 5. Package outline LGA-7x7-20-2 (sheet 2 of 2)

## 10. Handling information

#### **CAUTION**



This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices.

Such precautions are described in the ANSI/ESD S20.20, IEC/ST 61340-5, JESD625-A or equivalent standards.

Table 10. ESD sensitivity

ESD model	Class
Charged Device Model (CDM); According to ANSI/ESDA/JEDEC standard JS-002	C1 [1]
Human Body Model (HBM); According to ANSI/ESDA/JEDEC standard JS-001	1B [2]

- [1] CDM classification C1 is granted to any part that passes after exposure to an ESD pulse of 250 V.
- [2] HBM classification 1B is granted to any part that passes after exposure to an ESD pulse of 500 V.

### 11. Abbreviations

Table 11. Abbreviations

Acronym	Description		
CW	Continuous Wave		
ESD	ElectroStatic Discharge		
GSM	Global System for Mobile Communications		
LDMOS	Laterally Diffused Metal Oxide Semiconductor		
LTE	Long Term Evolution		
MMIC	Monolithic Microwave Integrated Circuit		
MTF	Median Time to Failure		
NR	New Radio		
ОВО	Output Back Off		
PAR	Peak-to-Average Ratio		
RoHS	Restriction of Hazardous Substances		
VBW	Video BandWidth		
VSWR	Voltage Standing Wave Ratio		
W-CDMA	Wideband Code Division Multiple Access		

## 12. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
B10G3336N16DL v.1	20230928	Product data sheet	-	-

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#### 13.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
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## B10G3336N16DL

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